L Number	Hits	Search Text	DB	Time stamp
1	87663	polyimide	USPAT;	2004/06/07 10:42
			US-PGPUB;	
			JРО	
2	199154	solder\$3	USPAT;	2004/06/07 10:43
			US-PGPUB;	
	Ì		JPO	
3	1053	ubm or "under bump"	USPAT;	2004/06/07 10:43
	1000	wone of white outling	US-PGPUB;	200 1100107 10110
			JPO	
4	39341	contact near2 pad\$1	USPAT;	2004/06/07 10:43
-	37541	contact near page 1	US-PGPUB;	2004/00/07 10:43
}		•	のS-I GF OD, IPO	
5	28379	reflow\$3		2004/06/07 10:44
5	203/9	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/06/07 10:44
			US-PGPUB;	
	100000	100	ЛРО	
6	198288	seed\$3 or nucleat\$3	USPAT;	2004/06/07 10:44
			US-PGPUB;	
			ΡΟ	
7	17886	solder\$3 same reflow\$3	USPAT;	2004/06/07 10:44
			US-PGPUB;	
			JPO	
8	88	(ubm or "under bump") same (seed\$3 or nucleat\$3)	USPAT;	2004/06/07 10:44
			US-PGPUB;	
			JPO	
9	629	solder\$3 same (ubm or "under bump")	USPAT;	2004/06/07 10:44
	""	bounded states (wont of analy states)	US-PGPUB;	200 1100107 10.11
			JPO	
10	25	polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump")	USPAT;	2004/06/07 10:45
10	25	same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under")	US-PGPUB;	2004/00/07 10.43
		bump"))	ло	
11	25	reflow\$3 and (polyimide and (solder\$3 same reflow\$3) and ((ubm or	1	2004/06/07 10:45
11	23		USPAT;	2004/00/07 10.43
	1	"under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or	US-PGPUB;	
21	0.7	"under bump")))	JPO	0004/06/07 11 10
21	27	polyimide and solder\$3 and (ubm or "under bump") and (contact near2	USPAT;	2004/06/07 11:18
}		pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)	US-PGPUB;	
			ЛРО	
22	11	(polyimide and solder\$3 and (ubm or "under bump") and (contact near2	USPAT;	2004/06/07 11:29
		pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and	US-PGPUB;	
	İ	(solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or	ЛО	
		nucleat\$3)) and (solder\$3 same (ubm or "under bump")))		
23	49	solder\$3 and (ubm or "under bump") and polyimide and reflow\$3 and	USPAT;	2004/06/07 11:30
		(seed\$3 or nucleat\$3)	US-PGPUB;	
			JPO	
24	36	(polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump")	USPAT;	2004/06/07 11:30
		same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under	US-PGPUB;	
	1	bump"))) ((polyimide and solder\$3 and (ubm or "under bump") and	JPO	
		(contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not		
	1	(polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump")		1
		same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under		
		bump"))))		1
25	13	(solder\$3 and (ubm or "under bump") and polyimide and reflow\$3 and	USPAT;	2004/06/07 11:30
		(seed\$3 or nucleat\$3)) not ((polyimide and (solder\$3 same reflow\$3))	US-PGPUB;	2004/00/07 11.30
		and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3	JPO	
	1	same (ubm or "under bump"))) ((polyimide and solder\$3 and (ubm or	110	
		"under bump") and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or		
	i	nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and ((ubm or		
		"under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or		
		"under bump")))))		
26	400	polyimide and solder\$3 and (ubm or "under bump")	USPAT;	2004/06/07 11:31
			US-PGPUB;	
l	1		JPO	

27	49	((polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump")	USPAT;	2004/06/07 11:31
		same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under	US-PGPUB;	
		bump"))) ((polyimide and solder\$3 and (ubm or "under bump") and	JPO	
		(contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not		
		(polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump")		
		same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under		
		bump"))))) ((solder\$3 and (ubm or "under bump") and polyimide and		
		reflow\$3 and (seed\$3 or nucleat\$3)) not ((polyimide and (solder\$3 same		
		reflow\$3) and ((ubm or "under bump") same (seed\$3 or nucleat\$3)) and		
		(solder\$3 same (ubm or "under bump"))) ((polyimide and solder\$3 and		
		(ubm or "under bump") and (contact near2 pad\$1) and reflow\$3 and		
	1	(seed\$3 or nucleat\$3)) not (polyimide and (solder\$3 same reflow\$3) and		
		((ubm or "under bump") same (seed\$3 or nucleat\$3)) and (solder\$3		
		same (ubm or "under bump"))))))		
28	351	(polyimide and solder\$3 and (ubm or "under bump")) not (((polyimide	USPAT;	2004/06/07 11:31
		and (solder\$3 same reflow\$3) and ((ubm or "under bump") same	US-PGPUB;	
		(seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump")))	JPO	
		((polyimide and solder\$3 and (ubm or "under bump") and (contact near2		
		pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not (polyimide and		
		(solder\$3 same reflow\$3) and ((ubm or "under bump") same (seed\$3 or		
	1	nucleat\$3)) and (solder\$3 same (ubm or "under bump"))))) ((solder\$3		
		and (ubm or "under bump") and polyimide and reflow\$3 and (seed\$3 or		
		nucleat\$3)) not ((polyimide and (solder\$3 same reflow\$3) and ((ubm or		
		"under bump") same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under bump"))) ((polyimide and solder\$3 and (ubm or "under bump")		
		and (contact near2 pad\$1) and reflow\$3 and (seed\$3 or nucleat\$3)) not		
		(polyimide and (solder\$3 same reflow\$3) and ((ubm or "under bump")		
		same (seed\$3 or nucleat\$3)) and (solder\$3 same (ubm or "under")		
		bump"))))))		
	ı	Outup 11111111	1	1